

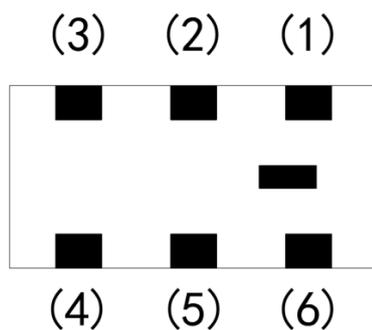
Features

- Multilayer monolithic construction yields high reliability
- Low insertion loss and small size SMD chip design
- Can simplify your complex tuning and circuit design
- LTCC process

Specifications

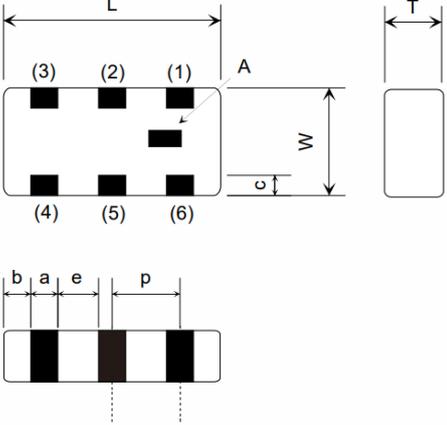
NO.	Parameter		SPEC	
			25°C	-40~+85°C
1	Insertion Loss (f1)	4900~5950 MHz	0.7 dB	0.8 dB
	Insertion Loss (f2)	2400~2500 MHz	0.6 dB	0.65 dB
2	Attenuation (f2)	4800~4992 MHz	32 dB	32 dB
		7200~7488 MHz	24 dB	24 dB
	Attenuation (f1)	30~2700 MHz	32 dB	32 dB
		9800~11900 MHz	15 dB	15 dB
		14700~17850 MHz	11 dB	11 dB
3	V.S.W.R (In BW)	1.80MAX		
4	Isolation	30~2700 MHz	32 dB	32 dB
		4900~5950 MHz	28 dB	28 dB
5	Port Impedance	50Ω		
6	Power	2.0 W max.		
7	Operation Temperature Range	-40°C ~ +90°C		

Construction

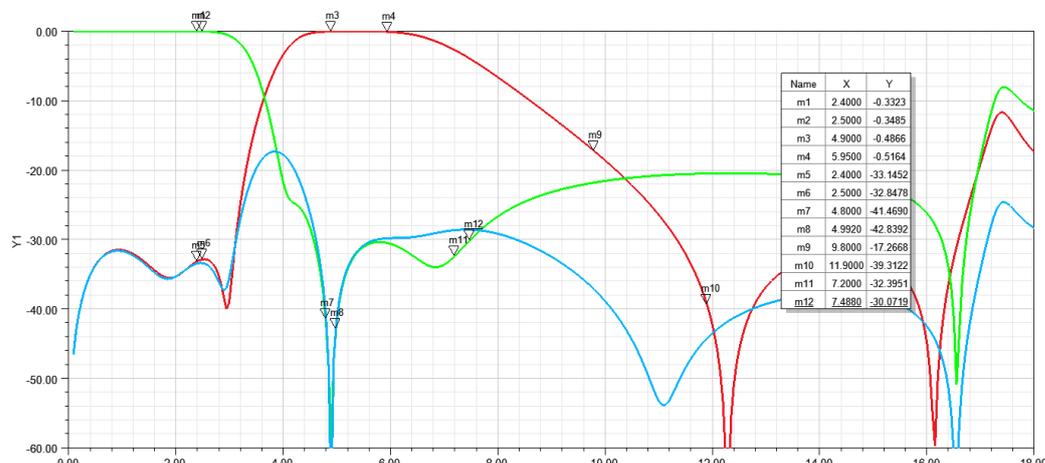
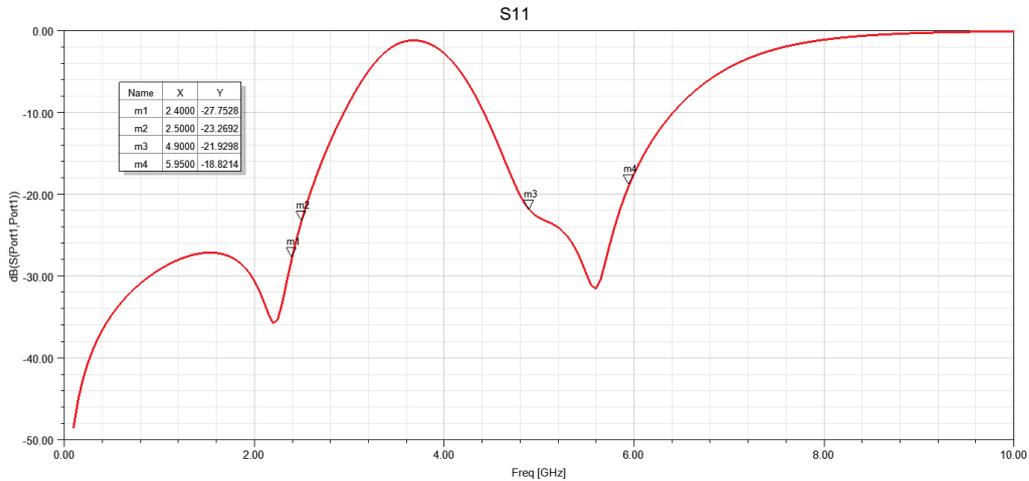


PIN	Connection	PIN	Connection
P1	GND	P4	Higher Port
P2	Common Port	P5	GND
P3	GND	P6	Low Port

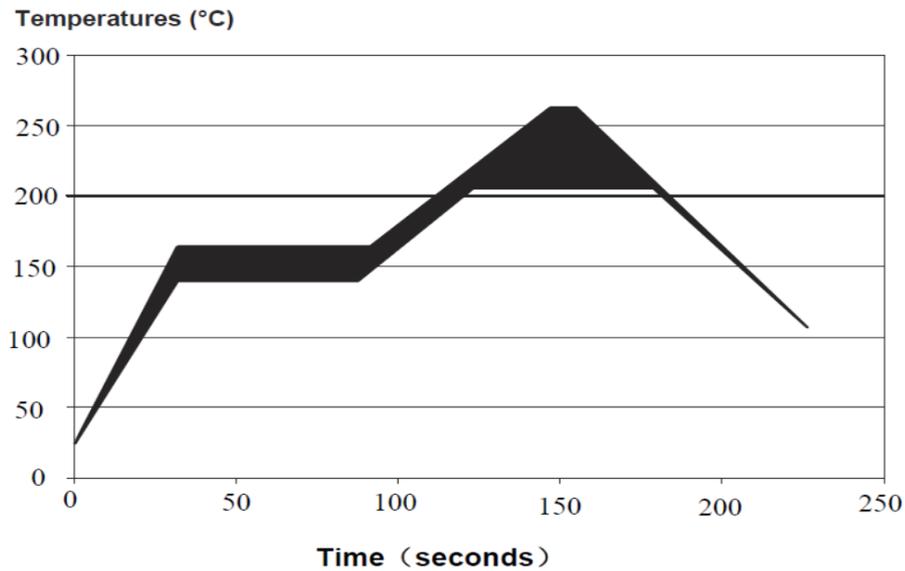
Dimensions

Figure	Symbol	Dimension (mm)
	L	1.60 ± 0.10
	W	0.80 ± 0.10
	T	0.7MAX
	A	0.20 ± 0.10
	B	0.20 ± 0.15
	C	0.15 ± 0.10
	E	0.30 ± 0.10
P	0.50 ± 0.05	

Typical Electrical Characteristics (T=25°C)



Solder Reflow Standard Conditioning



Storage Conditions

Temperature : +5 to +30 °C

Humidity : 20 to 70% RH

Term of storage : Within 12 months (After the delivery) *

Baking : Unnecessary

* After peeling off cover tape, do not keep exposing the products to the open air. For the products stored longer than 12 months, confirm their terminals and solderability before use.